

**Nominal frequency (f0)**

**10 MHz**

### Frequency stabilities

Parameter	Frequency stability	Operating temp. range
Over all (df/f0)	-4.6 to 4.6 ppm	
vs. operating temp. range (df/f@25 °C)	-10 to 10 ppb	-40 ... 85 °C
Additional information Drift 24 Hr and ±2.8°C temp. change < ±0.8ppb over all include: Temp Stab, supply, load stab, inital, 20 years aging S3E compliant according GR1244		
Parameter	Value	Condition
initial tolerance (df/f0)	-500 to 500 ppb	@ 25 °C
vs. supply voltage change (df/f)	-10 to 10 ppb	static; 3.3 V ±5 %
vs. load change (df/f)	-5 to 5 ppb	static; Load ± 5 %
vs. aging / daily (df/f)	<± 1 ppb	after 30 days ; @ 25 °C
vs. aging / month (df/f)	<± 25 ppb	after 30 days ; @ 25 °C
vs. aging / year (df/f)	<± 100 ppb	after 30 days ; @ 25 °C
vs. aging / 10 years (df/f)	<± 1 ppm	after 30 days ; @ 25 °C
Holdover 24 h	± 10 ppb	incl. Drift and -40..85°C temperature stability

### RF output

Parameter	Value	Condition
Signal	LVC MOS	
Load	15 pF ±10 %	
Fan out	3	
Rise Time	< 10 ns	@ 10 to 90 %Vout
Fall Time	< 10 ns	@ 90 to 10 %Vout
Duty cycle	45 / 55 %	@ 1.65 V
V Low	x < 0.4 V	
V High	x > 2.4 V	

### Supply voltage

Parameter	Value	Condition
Supply voltage (Vs)	3.3 V ± 5 %	
Current consumption steady state	< 400 mA	@ Vsnom & 25 °C
Current consumption during warm up	< 950 mA	@ Vs

### Additional Parameters

Parameter	Typ.	Max.	Condition
Phase Noise	-85	-60	dBc/Hz@1Hz
	-110	-90	dBc/Hz@10Hz
	-130	-115	dBc/Hz@100Hz
	-143	-130	dBc/Hz@1kHz
	-150	-145	dBc/Hz@10kHz
MTIE	0.2 ns		1 sec
	2.0 ns		10 sec
	10.0 ns		100 sec
	40.0 ns		1000 sec
Parameter	Value		Condition
Jitter	< 1.000 psec (RMS)		@ 12 kHz to 20 MHz
TDEV	0.01 ns		1 s
TDEV	0.1 ns		10 s
TDEV	1 ns		100 s
TDEV	3 ns		1000 s
Warm-up time	< 5 min		@ 25 °C to final frequency
Additional information TDEV: Typical Wander Generation performance when locked through a 1mHz system loop bandwidth Holdover 10ppb peak-peak: incl. of 24 h aging and a 40°C temperature change			
Processing & Packing	handling&processing note		

### Additional environmental conditions

Rapid temperature changes MIL-883-1010 Cond B 1000 cycles -55/125°C
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### Additional environmental conditions

Vibration
MIL-STD-883 Meth 2007 Cond A 20G 20-2000Hz 4x in each 3axis 4 min
Shock
MIL-STD-202 Meth 213 Cond.C 100G 6ms 6 shocks in each direction
Sealing test A
staubdicht (dust-dense)
Solderability
J_STD_002C Cond A, Through hole device/ Cond. B, SMD 255°C (diving time 5±0,5sec.) Dip+Look with 8h damp pre-treatment: solder wetting >95%
Solvent resistance
MIL-STD-883 Meth 2015 Solv. 1,3,4
ESD
HBM JESD22-A114-E Class 2 10* 2000V
Moisture Sensit.
Level 1 JESD22-A113-B
RoHS compliance
100% RoHS 6 compliant
Washable
non-washable device

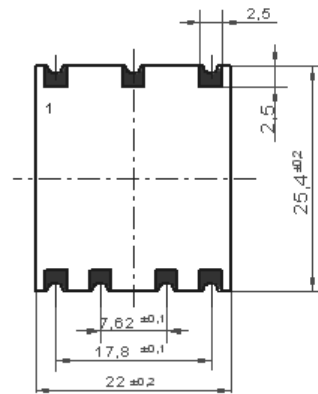
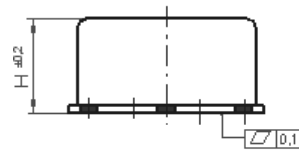
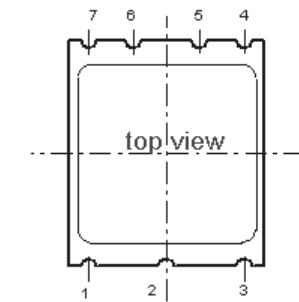
### Absolute Maximum Ratings

Parameter	Min	Typ	Max	Units	Condition
Operable temperature range	-40		85	°C	
Storage temperature range	-50		90	°C	

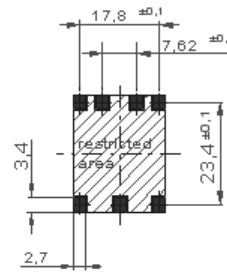
**Enclosure**

Type G185C

Height 12.1 mm



**G185**



Padvorschlag  
land pattern  
recommendation

all units in mm

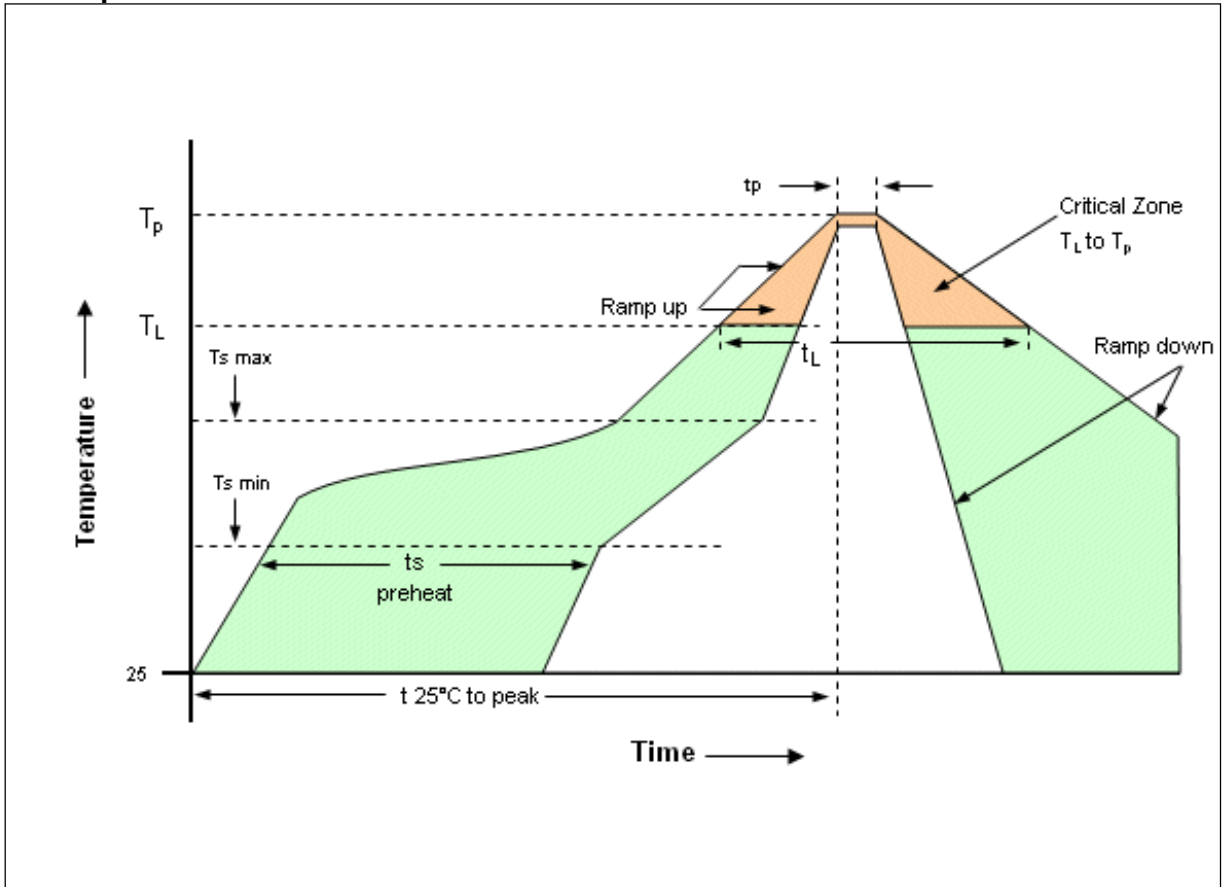
**Pin Connections**

- Pin 1: I.C. (=> do not connect)
- Pin 2: N.C.
- Pin 3: Vs (supply voltage)
- Pin 4: RF-Output
- Pin 5-6: N.C.
- Pin 7: GND (Case)

**Marking**

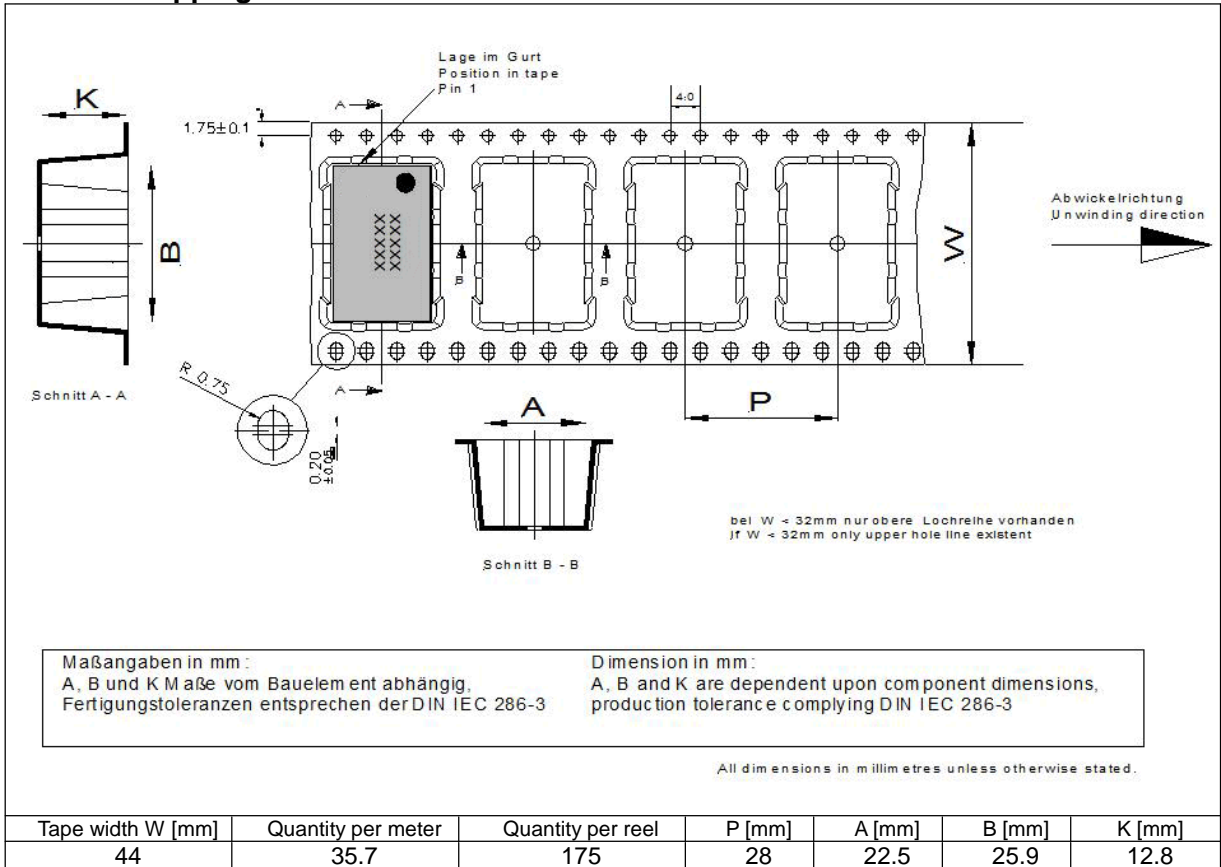
OX-2221-EAE-1080  
10M000  
Ser.No. AYYWW \*  
\* pin-1 marking

**Reflow profile**



Profile Feature	Pb-Free Assembly/Sn-Pb Assembly
Average ramp-up rate (TL to Tp)	3°C/second max.
Preheat -Temperature Min (T <sub>smin</sub> )	150°C
-Temperature Min (T <sub>smax</sub> )	200°C
-Time (min to max) (t <sub>s</sub> )	60-180 seconds
T <sub>smax</sub> to TL - Ramp-up Rate	3°C/second max.
Time maintained above - Temperature (TL)	217°C
- Time (t <sub>L</sub> )	60-150 seconds
Peak Temperature (T <sub>p</sub> )	max 260°C
Time within 5°C of actual Peak Temperature (t <sub>p</sub> )	20-40 seconds
Ramp-down Rate	6°C/second max.
Time 25°C to Peak Temperature	8 minutes max.
Note: All temperatures refer to topside of the package, measured on the package body surface.	
Additional Information	
This SMD oscillator has been designed for pick and place reflow soldering. SMD oscillators must be on the top side of the PCB during the reflow process.	

**Standard shipping method**



**Notes:**

Unless otherwise stated all values are valid after warm-up time and refer to typical conditions for supply voltage, frequency control voltage, load, temperature (25°C) .  
Subject to technical modification.

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